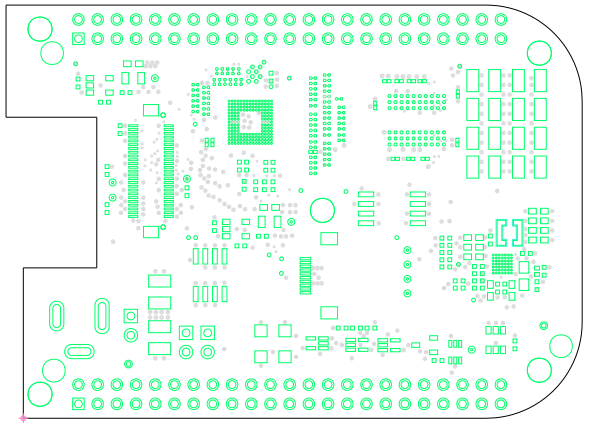
ART FILM - 111609-01_smt

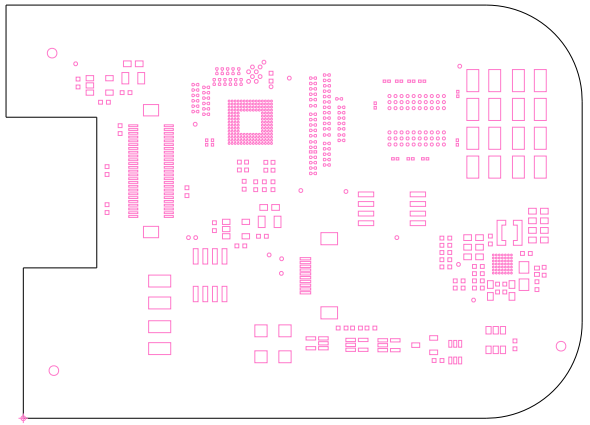


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SOLDERMASK - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 7	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X SOLDERMASK TOP		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_smt

ART FILM - 111609-01_spt

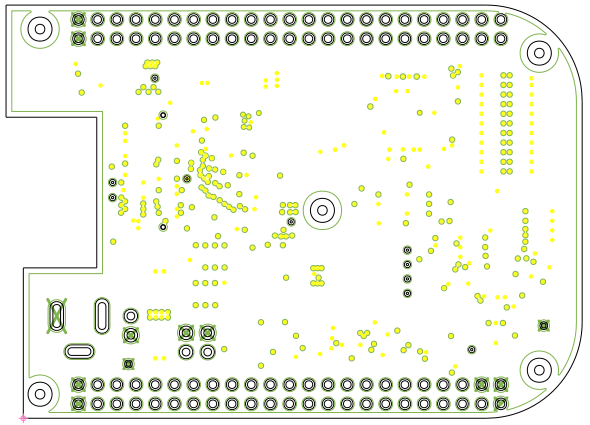


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SOLDERPASTE - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 11	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X SOLDERPASTE TOP		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_spt

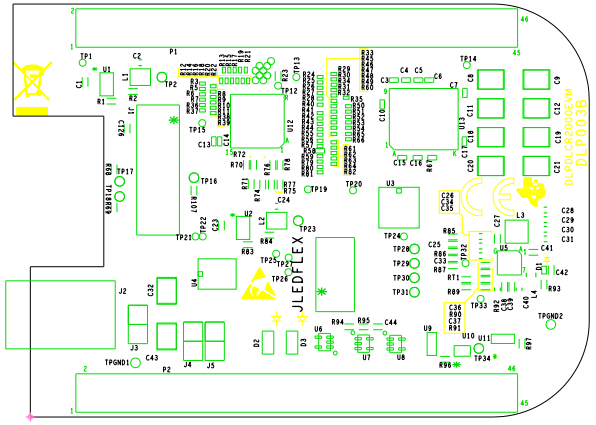
ART FILM - 111609-01_ly5



CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 5 - GND PLANE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 5	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 5 - GND PLANE		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

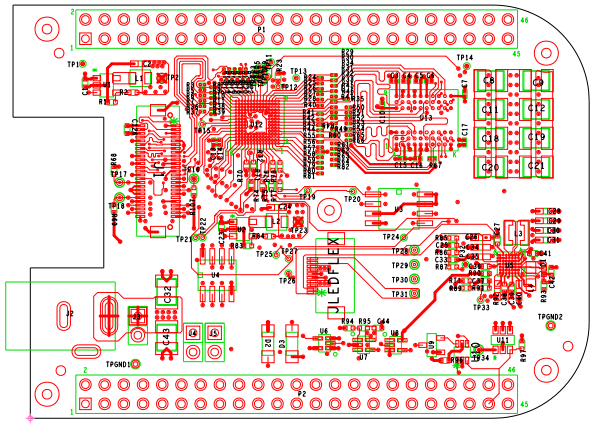
ART FILM - 111609-01_ly5



CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SILKSCREEN - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 9	OF: 13

SILKSCREEN TOP

ART FILM - 111609-01_top

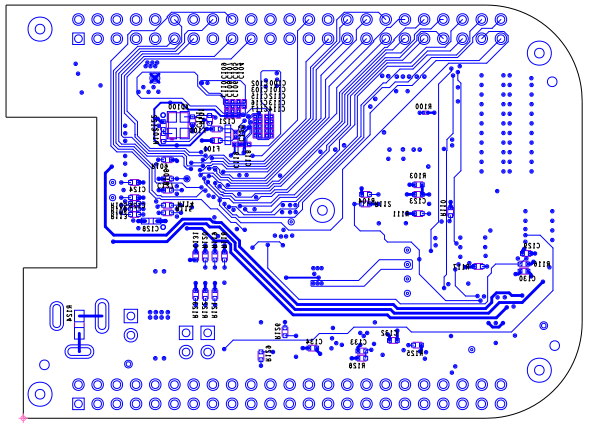


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 1 - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 1	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 1 - TOP		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_top

ART FILM - 111609-01_bot

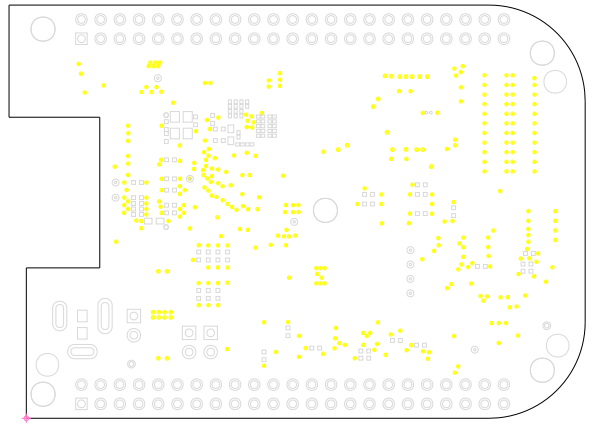


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 6 - SECONDARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 6	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 6 - BOTTOM		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_bot

ART FILM - 111609-01_smb

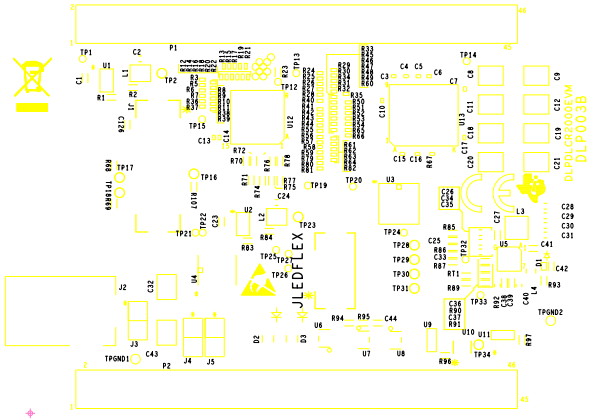


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM			DESCRIPTION: SOLDERMASK - SECONDARY SIDE		
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 8	OF: 13

CUSTOMER: TEXAS INSTRUMENTS				KSID: 17745	JOB NUMBER: 131881
BOARD NAME: DLPDLCR2000EVM			LAYER DESCRIPTION: X SOLDERMASK BOTTOM		
ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX	

ART FILM - 111609-01_smb

ART FILM - 111609-01_sst

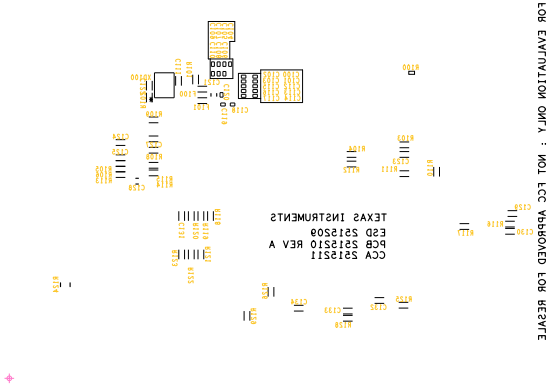


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SILKSCREEN - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 9	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X SILKSCREEN TOP		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_sst

ART FILL - 111609-01_ssb

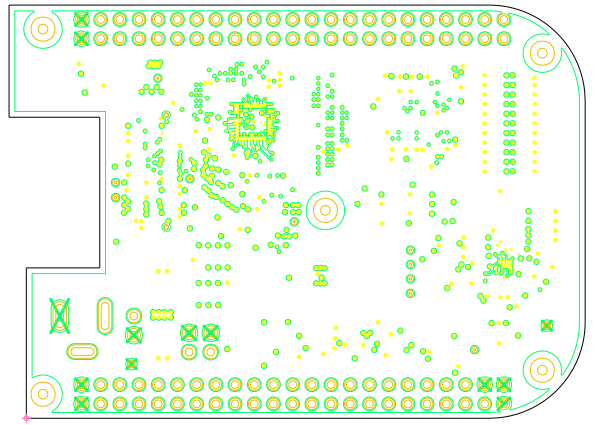


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SILKSCREEN - SECONDARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 10	OF: 13

CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881	
BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X SILKSCREEN BOTTOM			
ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX	

ART FILL - 111609-01_ssb

ART FILM - 111609-01_ly2

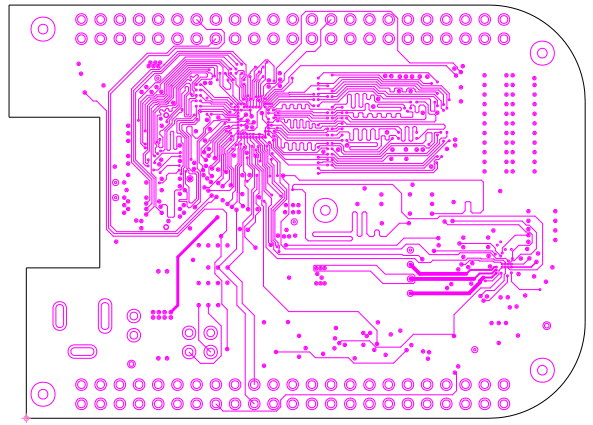


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM			DESCRIPTION: LAYER 2 - GND PLANE		
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 2	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 2 - GND PLANE		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_ly2

ART FILM - 111609-01_ly3

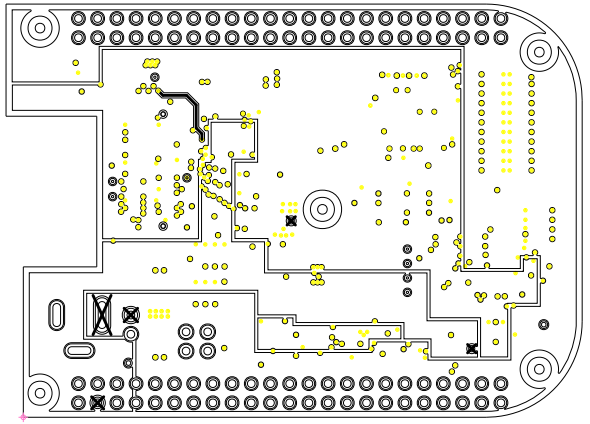


CUSTOMER NAME	TEXAS INSTRUMENTS				
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 3 - SIGNAL			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 3	OF: 13

CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881	
BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 3 - SIGNAL			
ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX	

ART FILM - 111609-01_ly3

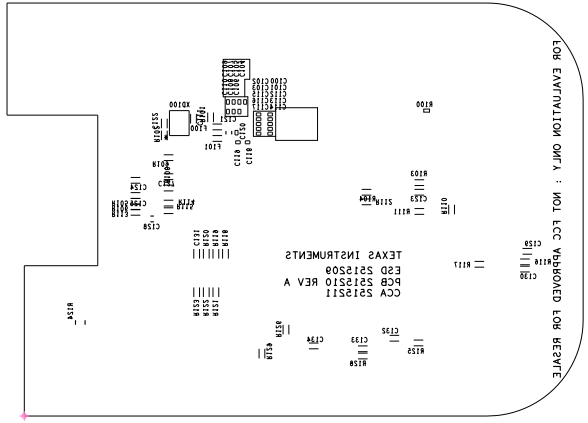
ART FILM - 111609-01_ly4



CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 4 - PWR PLANE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 4	OF: 13

krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X LAYER 4 - GND PLANE		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_ly4



CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM			DESCRIPTION: SILKSCREEN - SECONDARY SIDE		
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 10	OF: 13

SILKSCREEN BOTTOM

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	8.0	+0.0/-8.0	PLATED	320
·	8.0	+3.0/-8.0	PLATED	1
·	9.0	+0.0/-0.0	PLATED	12
+	10.0	+0.0/-10.0	PLATED	17
□	12.0	+3.0/-12.0	PLATED	10
○	24.0	+0.0/-0.0	PLATED	2
□	40.0	+0.0/-0.0	PLATED	3
○	40.0	+3.0/-3.0	PLATED	95
○	23.622	+1.969/-0.0	NON-PLATED	2
⊣⊢	125.0	+0.0/-0.0	NON-PLATED	5
⬯	120.0x40.0	+3.0/-3.0	PLATED	1
⬭	120.0x40.0	+3.0/-3.0	PLATED	1
⬯	140.0x40.0	+3.0/-3.0	PLATED	1

DRILL CHART: TOP to LY2

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	61

DRILL CHART: TOP to LY3

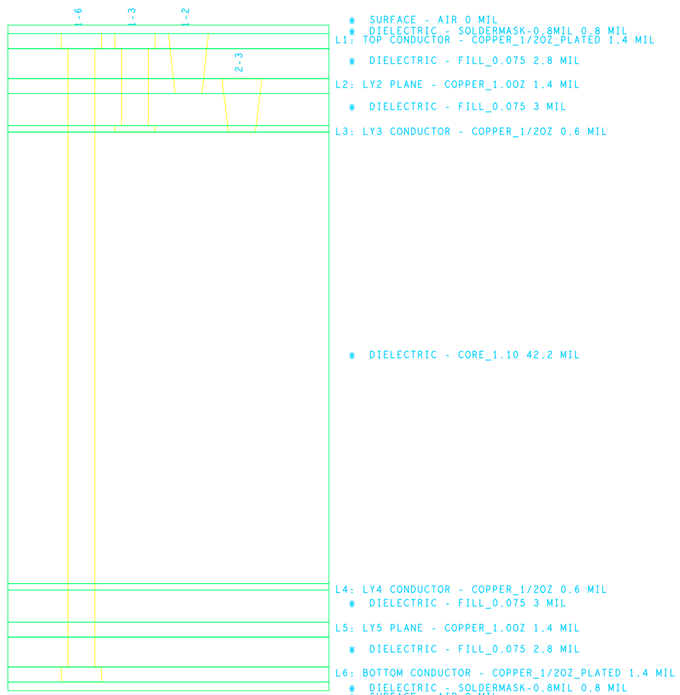
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	221

DRILL CHART: LY2 to LY3

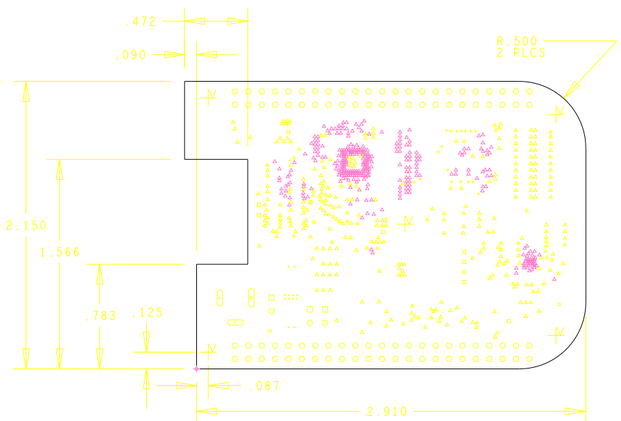
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	48



* SURFACE - AIR 0 MIL
* DIELECTRIC - SOLDERMASK-0.8MIL 0.8 MIL
L1: TOP CONDUCTOR - COPPER_1/2OZ_PLATED 1.4 MIL
* DIELECTRIC - FILL_0.075 2.8 MIL
L2: LY2 PLANE - COPPER_1.0OZ 1.4 MIL
* DIELECTRIC - FILL_0.075 3 MIL
L3: LY3 CONDUCTOR - COPPER_1/2OZ 0.6 MIL
* DIELECTRIC - CORE_1.10 42.2 MIL
L4: LY4 CONDUCTOR - COPPER_1/2OZ 0.6 MIL
* DIELECTRIC - FILL_0.075 3 MIL
L5: LY5 PLANE - COPPER_1.0OZ 1.4 MIL
* DIELECTRIC - FILL_0.075 2.8 MIL
L6: BOTTOM CONDUCTOR - COPPER_1/2OZ_PLATED 1.4 MIL
* DIELECTRIC - SOLDERMASK-0.8MIL 0.8 MIL
* SURFACE - AIR 0 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 62.2 MIL



FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
4. BOARD MATERIAL & CONSTRUCTION MUST MEET OR EXCEED UL94V-0. PCB MUST HAVE UL REGISTERED MATERIAL ID ON THE PCB.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. VIAS CAN CONFORM TO CLASS 2 REQUIREMENTS AND SHOULD BE TEARDROPPED BY FAB VENDOR.
10. MICRO VIAS TO BE FILLED AND PLANARIZED PRIOR TO PLATING, VENDOR TO DETERMINE METHOD.

PROCESS NOTES:

1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK GOLD 2-10 MICROINCHES THK MIN.
2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

LAYER STACK:

LAYER 1 - TOP SIDE, 3/8oz Cu START
50 OHMS SE - 0.0052
100 OHMS DIFF 0.004 WIDTH/0.007 SPACE

LAYER 2 - GND PLANE, 3/8oz Cu

LAYER 3 - SIGNAL, 1/2oz Cu
50 OHMS SE - 0.0052

LAYER 4 - PWR PLANE, 1/2oz Cu

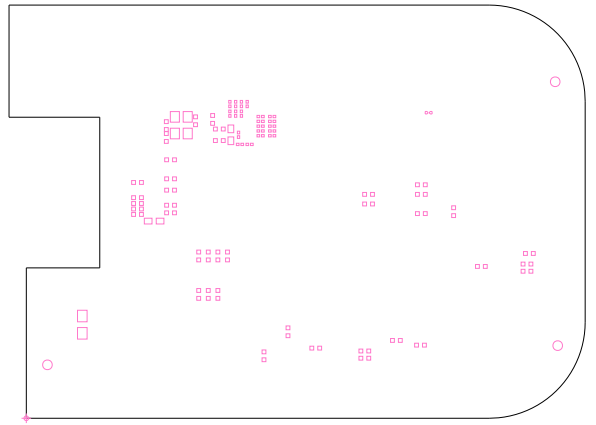
LAYER 5 - GND PLANE, 3/8oz Cu

LAYER 6 - BOTTOM SIDE, 3/8oz Cu START
50 OHMS SE - 0.0052

CUSTOMER NAME: TEXAS INSTRUMENTS				
BOARD NAME: nHD EVM		DESCRIPTION: DRILL DRAWING		
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 13 OF 13

CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X		
ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

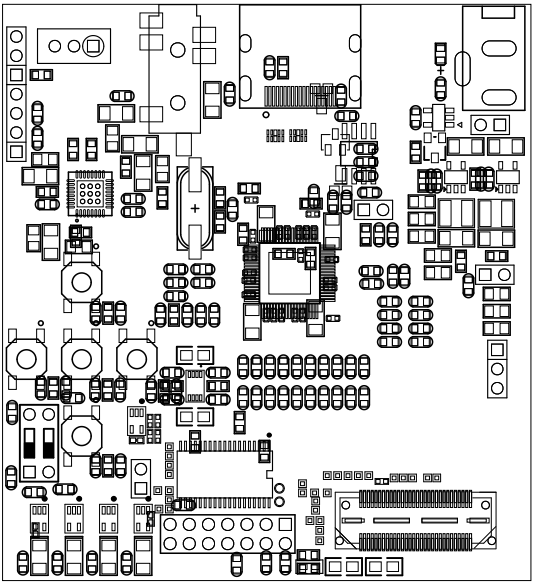
ART FILM - 111609-01_spb

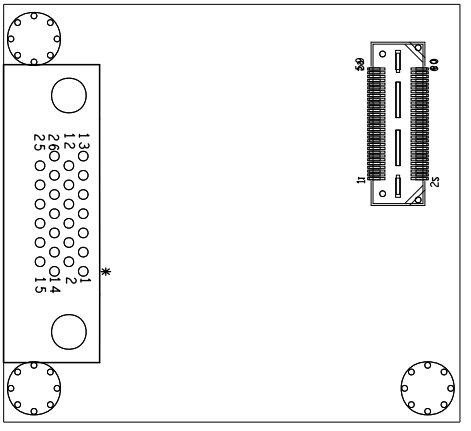


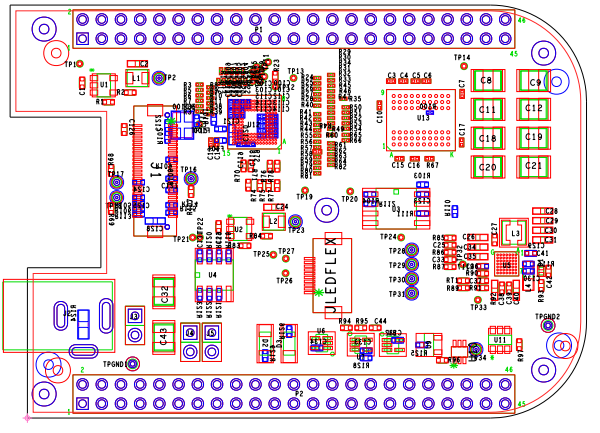
CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SOLDERPASTE - SECONDARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 12	OF: 13

Krypton systems	CUSTOMER: TEXAS INSTRUMENTS			KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X		
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

ART FILM - 111609-01_spb

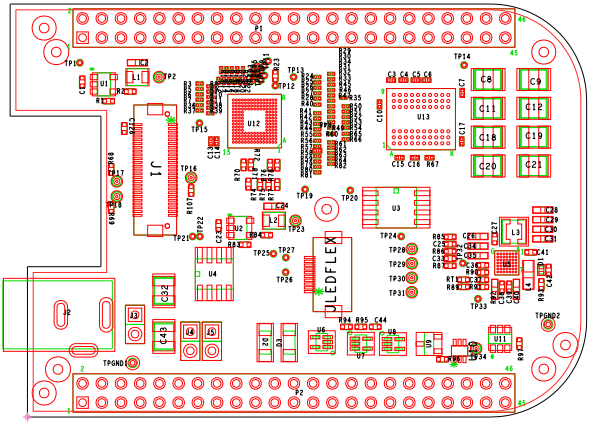






CUSTOMER NAME	TEXAS INSTRUMENTS				
BOARD NAME nHD EVM		DESCRIPTION			
BOARD NO. 2515210	REV E2	DATE 16-MAR-2017	PRJ# TIDLP-111609-01	SH	OF 13

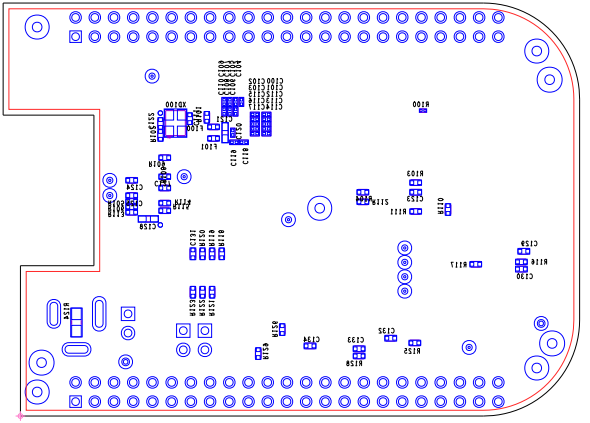
ART FILM - PLACE_TOP



CUSTOMER NAME	TEXAS INSTRUMENTS				
BOARD NAME	nHD EVM	DESCRIPTION			
BOARD NO. 2515210	REV E2	DATE 16-MAR-2017	PRJ# TIDLP-111609-01	SH	OF 13

ART FILM - PLACE_TOP

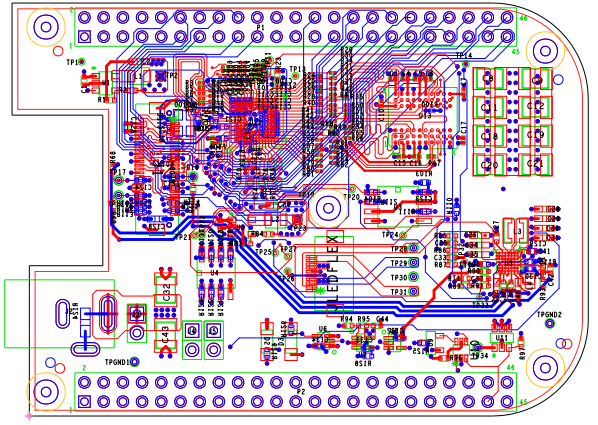
ART FILM - PLACE_BOT



CUSTOMER NAME	TEXAS INSTRUMENTS				
BOARD NAME nHD EVM		DESCRIPTION			
BOARD NO. 2515210	REV E2	DATE 16-MAR-2017	PRJ# TIDLP-111609-01	SH	OF 13

ART FILM - PLACE_BOT

ART FILM - ROUTING



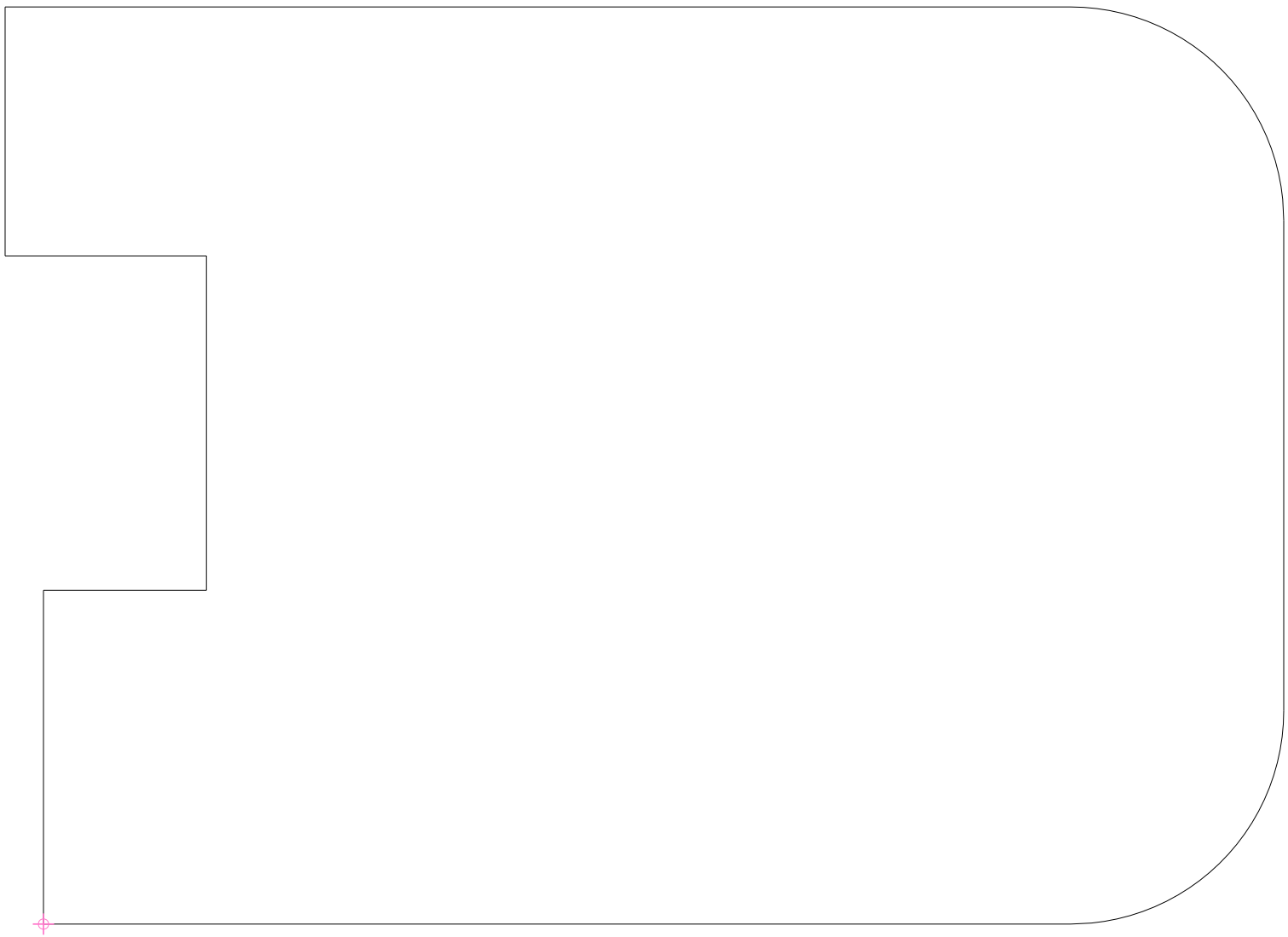
CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: LAYER 6 - SECONDARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 6	OF: 13

LAYER 6 - SECONDARY SIDE

LAYER 6 - BOTTOM

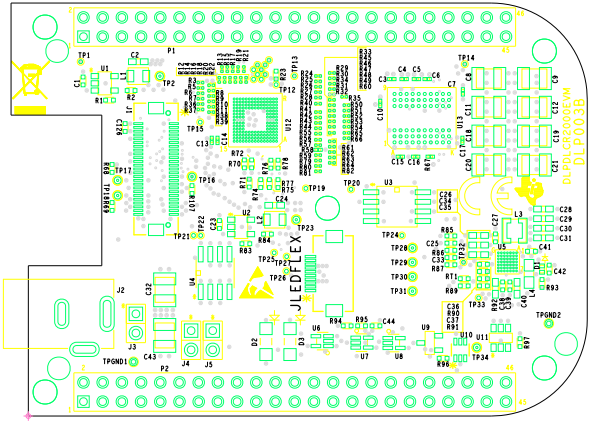
ART FILM - ROUTING

ART FILM - outline



ART FILM - outline

ART FILM - TSS_NO_PLOT

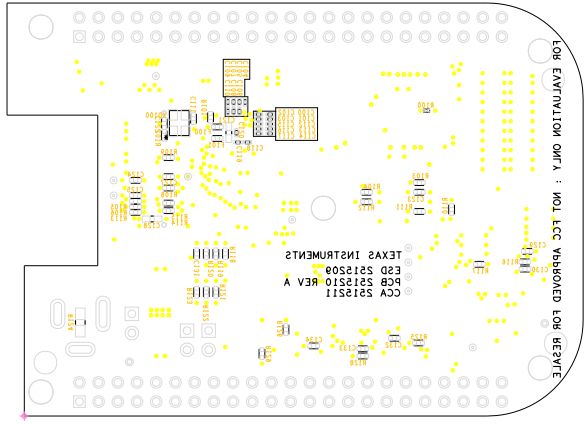


CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM		DESCRIPTION: SILKSCREEN - PRIMARY SIDE			
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 9	OF: 13

SILKSCREEN TOP

ART FILM - TSS_NO_PLOT

ART FILL - BSS_NO_PLOT



CUSTOMER NAME: TEXAS INSTRUMENTS					
BOARD NAME: nHD EVM			DESCRIPTION: SILKSCREEN - SECONDARY SIDE		
BOARD NO.: 2515210	REV: E2	DATE: 16-MAR-2017	PRJ#: TIDLP-111609-01	SH: 10	OF: 13

SILKSCREEN BOTTOM

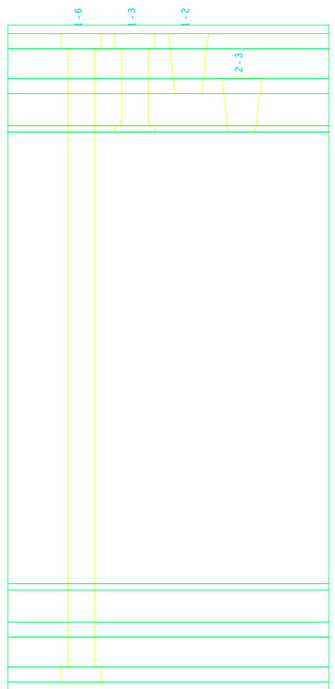
ART FILL - BSS_NO_PLOT

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	8.0	+0.0/-8.0	PLATED	320
·	8.0	+3.0/-8.0	PLATED	1
·	9.0	+0.0/-0.0	PLATED	12
+	10.0	+0.0/-10.0	PLATED	17
□	12.0	+3.0/-12.0	PLATED	10
○	24.0	+0.0/-0.0	PLATED	2
□	40.0	+0.0/-0.0	PLATED	3
○	40.0	+3.0/-3.0	PLATED	95
○	23.622	+1.969/-0.0	NON-PLATED	2
⊣⊢	125.0	+0.0/-0.0	NON-PLATED	5
⬭	120.0x40.0	+3.0/-3.0	PLATED	1
⬭	120.0x40.0	+3.0/-3.0	PLATED	1
⬭	140.0x40.0	+3.0/-3.0	PLATED	1

DRILL CHART: TOP to LY2				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	61

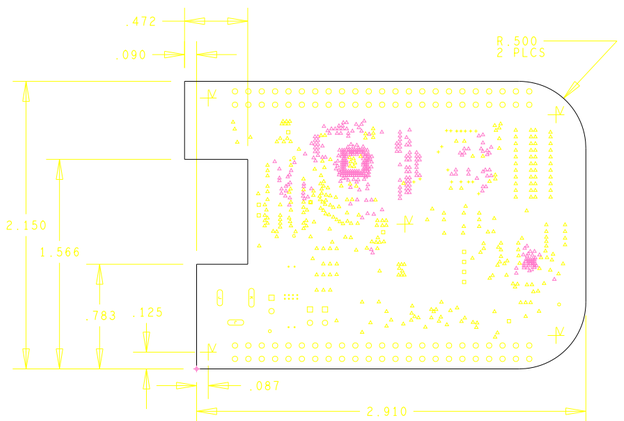
DRILL CHART: TOP to LY3				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	221

DRILL CHART: LY2 to LY3				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	4.0	+0.0/-4.0	PLATED	48



- * SURFACE - AIR 0 MIL
- * DIELECTRIC - SOLDERMASK-0.8MIL 0.8 MIL
- L1: TOP CONDUCTOR - COPPER_1/2OZ_PLATED 1.4 MIL
- * DIELECTRIC - FILL_0.075 2.8 MIL
- L2: LY2 PLANE - COPPER_1.0OZ 1.4 MIL
- * DIELECTRIC - FILL_0.075 3 MIL
- L3: LY3 CONDUCTOR - COPPER_1/2OZ 0.6 MIL
- * DIELECTRIC - CORE_1.10 42.2 MIL
- L4: LY4 CONDUCTOR - COPPER_1/2OZ 0.6 MIL
- * DIELECTRIC - FILL_0.075 3 MIL
- L5: LY5 PLANE - COPPER_1.0OZ 1.4 MIL
- * DIELECTRIC - FILL_0.075 2.8 MIL
- L6: BOTTOM CONDUCTOR - COPPER_1/2OZ_PLATED 1.4 MIL
- * DIELECTRIC - SOLDERMASK-0.8MIL 0.8 MIL
- * SURFACE - AIR 0 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 62.2 MIL



FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
4. BOARD MATERIAL & CONSTRUCTION MUST MEET OR EXCEED UL94V-0. PCB MUST HAVE UL REGISTERED MATERIAL ID ON THE PCB.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. VIAS CAN CONFORM TO CLASS 2 REQUIREMENTS AND SHOULD BE TEARDROPPED BY FAB VENDOR.
10. MICRO VIAS TO BE FILLED AND PLANARIZED PRIOR TO PLATING, VENDOR TO DETERMINE METHOD.

PROCESS NOTES:

1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK GOLD 2-10 MICROINCHES THK MIN.
2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

LAYER STACK:

- LAYER 1 - TOP SIDE, 3/8oz Cu START
  50 OHMS SE - 0.0052
  100 OHMS DIFF 0.004 WIDTH/0.007 SPACE
- LAYER 2 - GND PLANE, 3/8oz Cu
- LAYER 3 - SIGNAL, 1/2oz Cu
  50 OHMS SE - 0.0052
- LAYER 4 - PWR PLANE, 1/2oz Cu
- LAYER 5 - GND PLANE, 3/8oz Cu
- LAYER 6 - BOTTOM SIDE, 3/8oz Cu START
  50 OHMS SE - 0.0052

DRILL DRAWING

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Krypton systems	CUSTOMER: TEXAS INSTRUMENTS		KSID: 17745	JOB NUMBER: 131881
	BOARD NAME: DLPDLCR2000EVM		LAYER DESCRIPTION: X	
	ENGINEER: Philippe Dollo	PCB DESIGNER: Lynn Witter	BOARD REV: B	RELEASE DATE: MAR-27-2018	SHEET NUMBER: XX of XX

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